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(71) Applicant (for all designated States except US): **LAM RESEARCH CORPORATION** [US/US]; 4650 Cushing Parkway, Fremont, California 94538 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **DHINDSA, Rajinder** [US/US]; 4650 Cushing Parkway, Fremont, CA 94538 (US). **ROGERS, James H.** [US/US]; 4650 Cushing Parkway, Fremont, CA 94538 (US).

(74) Agent: **NGUYEN, Joseph A.**; P.O. Box 700640, San Jose, CA 95170 (US).

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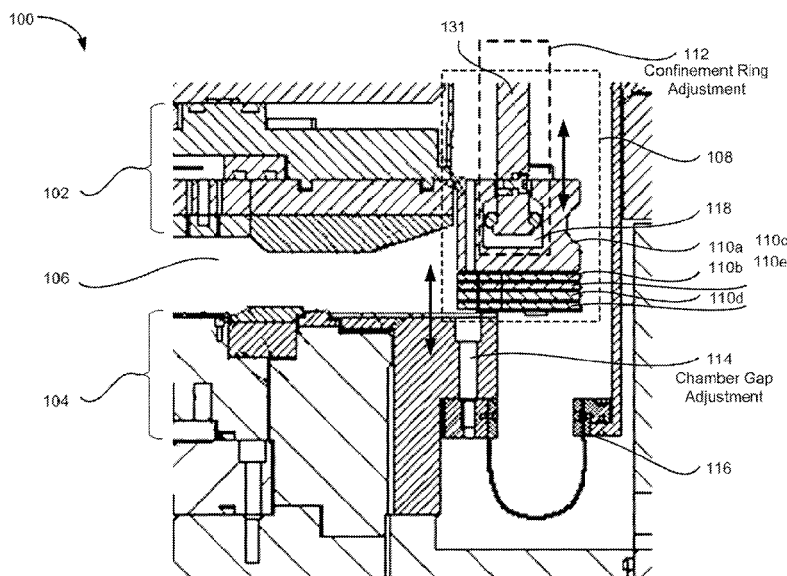


FIG. 1

(57) Abstract: In a plasma processing chamber, a method and an arrangement to stabilize pressure are provided. The method includes providing coarse pressure adjustments in an open-loop manner and thereafter providing fine pressure adjustments in a closed-loop manner. The coarse pressure adjustments are performed by rapidly reposition confinement rings employing an assumed linear relationship between the conductance and the confinement rings position to bring the pressure in the plasma generating region quickly to roughly a desired set point. The fine pressure adjustments are performed by at least employing mechanical vacuum pump(s), turbo pump(s), confinement ring positioning and/or combinations thereof to achieve a derive pressure set point.